

AMENDMENTS TO THE CLAIMS:

Claims 1-21 (cancelled)

22. (Previously presented) A polishing apparatus comprising:
a polishing tool;
a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool;
a first failure detection sensor disposed inside of said substrate holding member for detecting a failure of the substrate; and
a second failure detection sensor disposed outside of said substrate holding member for detecting a failure of the substrate.

Claim 23 (cancelled)

24. (Currently amended) ~~The polishing apparatus according to claim 4, further comprising:~~
A polishing apparatus comprising:
a polishing tool;
a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool, said substrate holding member including a guide ring for holding an outer periphery of the substrate;
a first failure detection sensor for detecting a failure of the substrate inside of said guide ring continually during polishing of the substrate, said first failure detection sensor being disposed at said substrate holding member or in the vicinity of said substrate holding member;
a second failure detection sensor for detecting a failure of the substrate under said guide ring;
a third failure detection sensor for detecting a failure of the substrate outside of said substrate holding member; and
a control unit to compare values measured by said first, second and third failure detection sensors with threshold values, respectively, and determine a failure of the substrate while polishing

the substrate in the event that any one of the values measured by said first, second and third failure detection sensors exceeds a respective one of the threshold values.

25. (Currently amended) ~~The polishing apparatus according to claim 4, further comprising:~~

A polishing apparatus comprising:

a polishing tool;

a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool, said substrate holding member including a guide ring for holding an outer periphery of the substrate;

a first failure detection sensor for detecting a failure of the substrate inside of said guide ring continually during polishing of the substrate, said first failure detection sensor being disposed at said substrate holding member or in the vicinity of said substrate holding member;

a second failure detection sensor for detecting a failure of the substrate under said guide ring;

a third failure detection sensor for detecting a failure of the substrate outside of said substrate holding member; and

a control unit to compare waveform patterns in values measured by said first, second and third failure detection sensors with predetermined waveform patterns, respectively, and determine a failure of the substrate while polishing the substrate in the event that any one of the waveform patterns in the values measured by said first, second and third failure detection sensors agrees with a respective one of the predetermined waveform patterns.

26. (Currently amended) ~~The polishing apparatus according to claim 11, further comprising:~~

A polishing apparatus comprising:

a polishing tool;

a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool;

at least two failure detection sensors for detecting a failure of the substrate in a radial direction of said substrate holding member continually during polishing of the substrate; and

a control unit to compare values measured by each of said at least two failure detection sensors with threshold values, respectively, and determine a failure of the substrate while polishing the substrate in the event that any one of the values measured by said each of said at least two failure detection sensors exceeds a respective one of the threshold values.

27. (Currently amended) ~~The polishing apparatus according to claim 11, further comprising:~~

A polishing apparatus comprising:

a polishing tool;

a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool;

at least two failure detection sensors for detecting a failure of the substrate in a radial direction of said substrate holding member continually during polishing of the substrate; and

a control unit to compare waveform patterns in values measured by each of said at least two failure detection sensors with predetermined waveform patterns, respectively, and determine a failure of the substrate while polishing the substrate in the event that any one of the waveform patterns in the values measured by said each of said at least two failure detection sensors agrees with a respective one of the predetermined waveform patterns.

28. (Currently amended) ~~The polishing apparatus according to claim 15, further comprising:~~

A polishing apparatus comprising:

a polishing tool;

a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool;

a first failure detection sensor for detecting a failure of the substrate inside of said substrate holding member;

a second failure detection sensor for detecting a failure of the substrate outside of said substrate holding member; and

a control unit to compare values measured by said first and second failure detection sensors with threshold values, respectively, and determine a failure of the substrate while polishing the

substrate in the event that any one of the values measured by said first and second failure detection sensors exceeds a respective one of the threshold values.

29. (Currently amended) ~~The polishing apparatus according to claim 15, further comprising:~~

A polishing apparatus comprising:

a polishing tool;

a substrate holding member to hold a substrate and to press a surface of the substrate against said polishing tool;

a first failure detection sensor for detecting a failure of the substrate inside of said substrate holding member;

a second failure detection sensor for detecting a failure of the substrate outside of said substrate holding member; and

a control unit to compare waveform patterns in values measured by said first and second failure detection sensors with predetermined waveform patterns, respectively, and determine a failure of the substrate while polishing the substrate in the event that any one of the wave form patterns in the values measured by said first and second failure detection sensors agrees with a respective one of the predetermined waveform patterns.

Claim 30 (cancelled)